

ESB & DAQ

Progress Report

Z. Papandreou
BIC General Meeting
March 14, 2025

ESB Napkin Sketch - Electron End

Legend:

PbScFi

Astropix

Light Guides

Cookies

SiPMs

Cooling

CALOROC

ETC

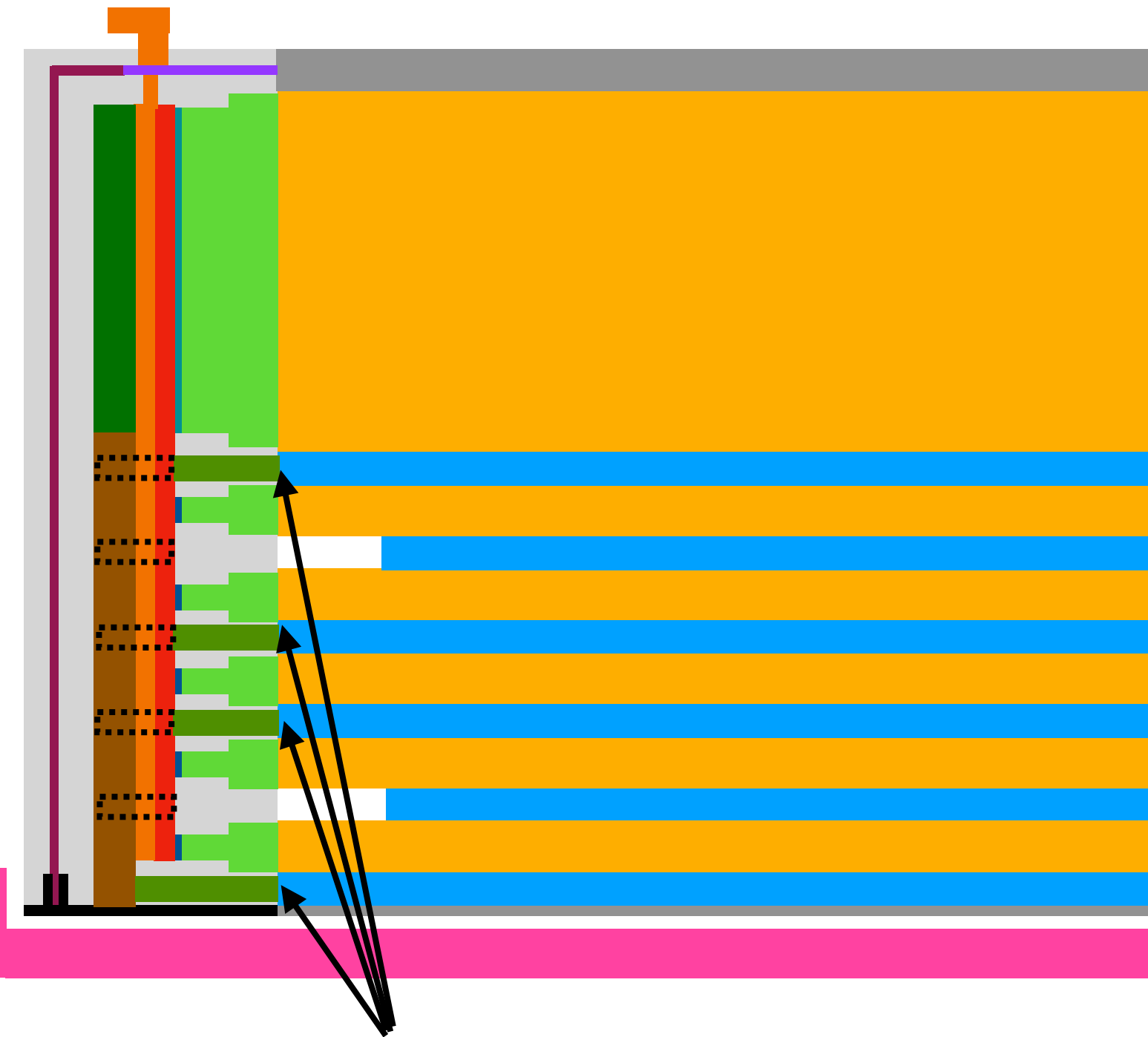
ETC cable

Top plate

Bottom plate

End plate

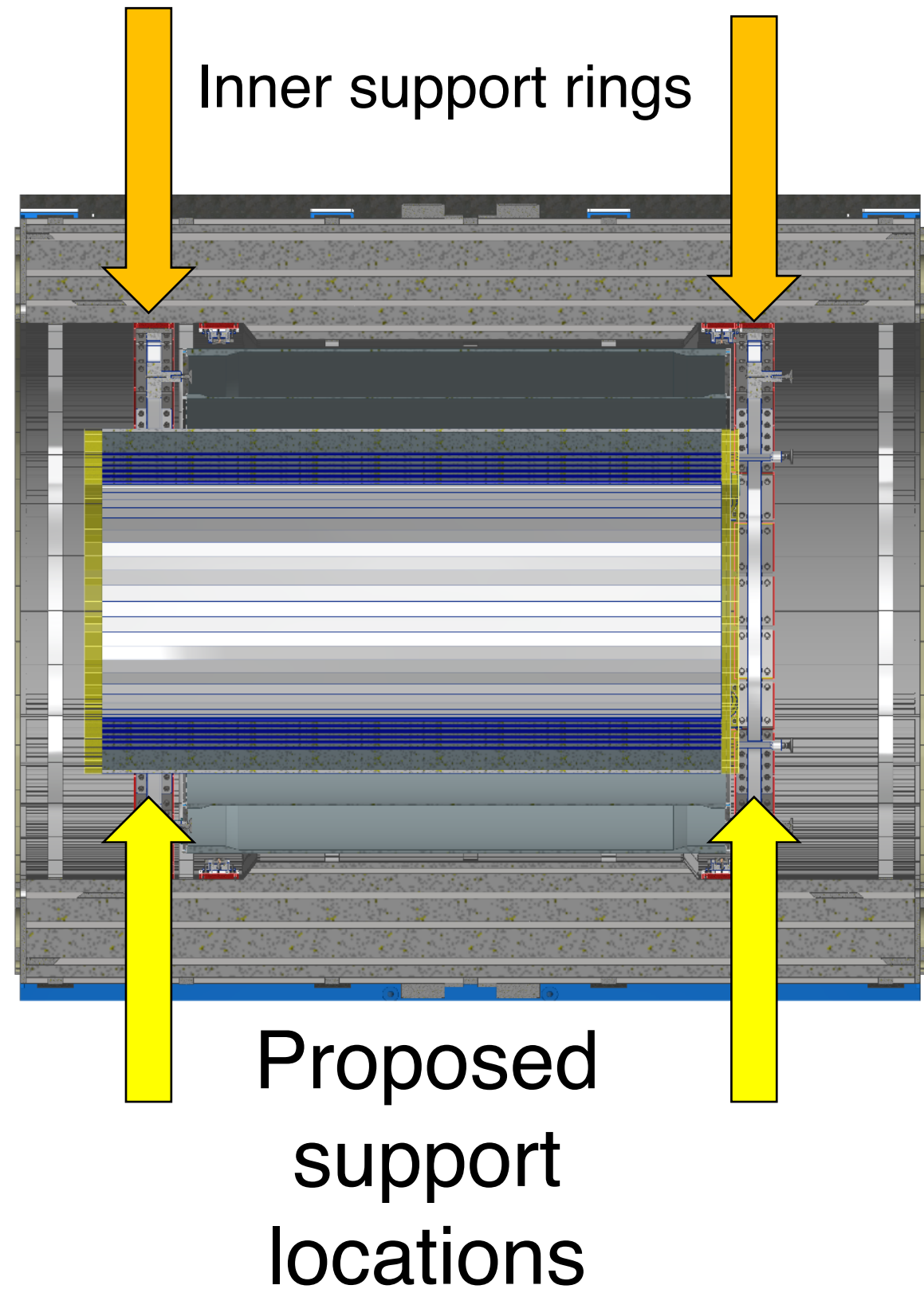
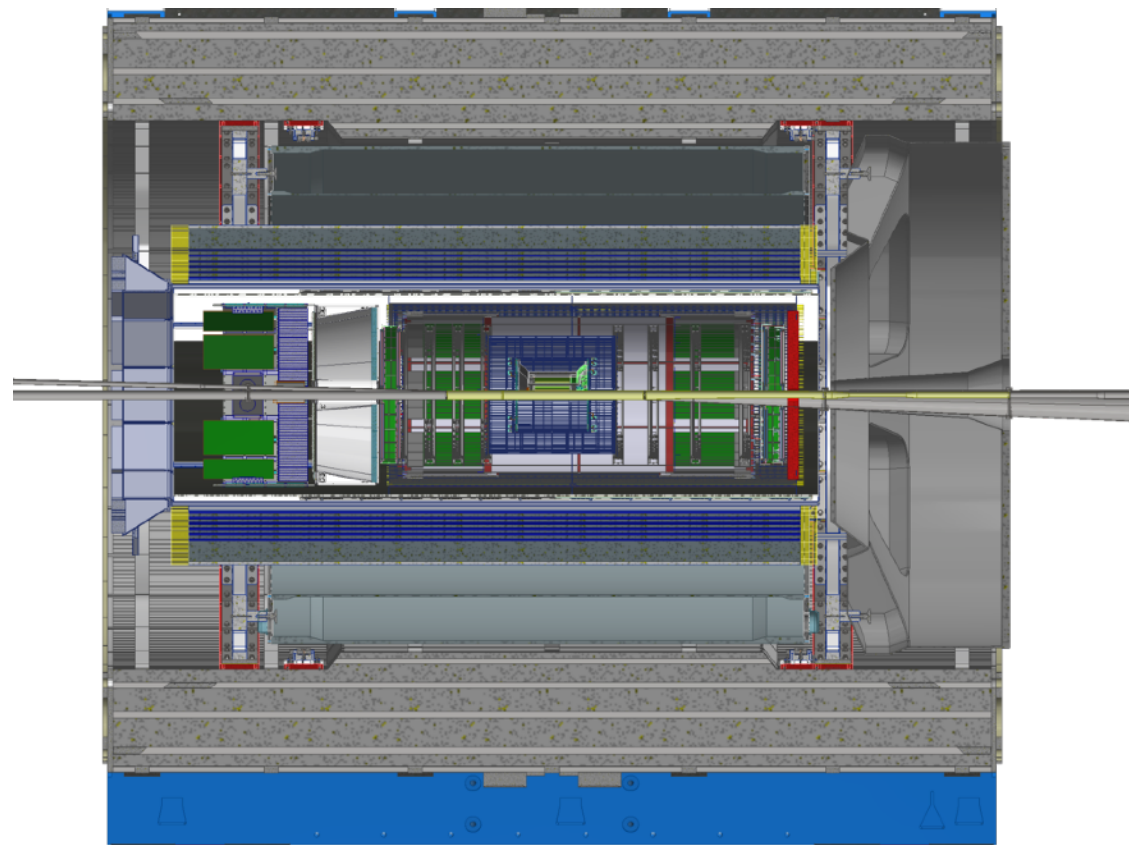
(Nasty)
DIRC



ETC to Astropix connector

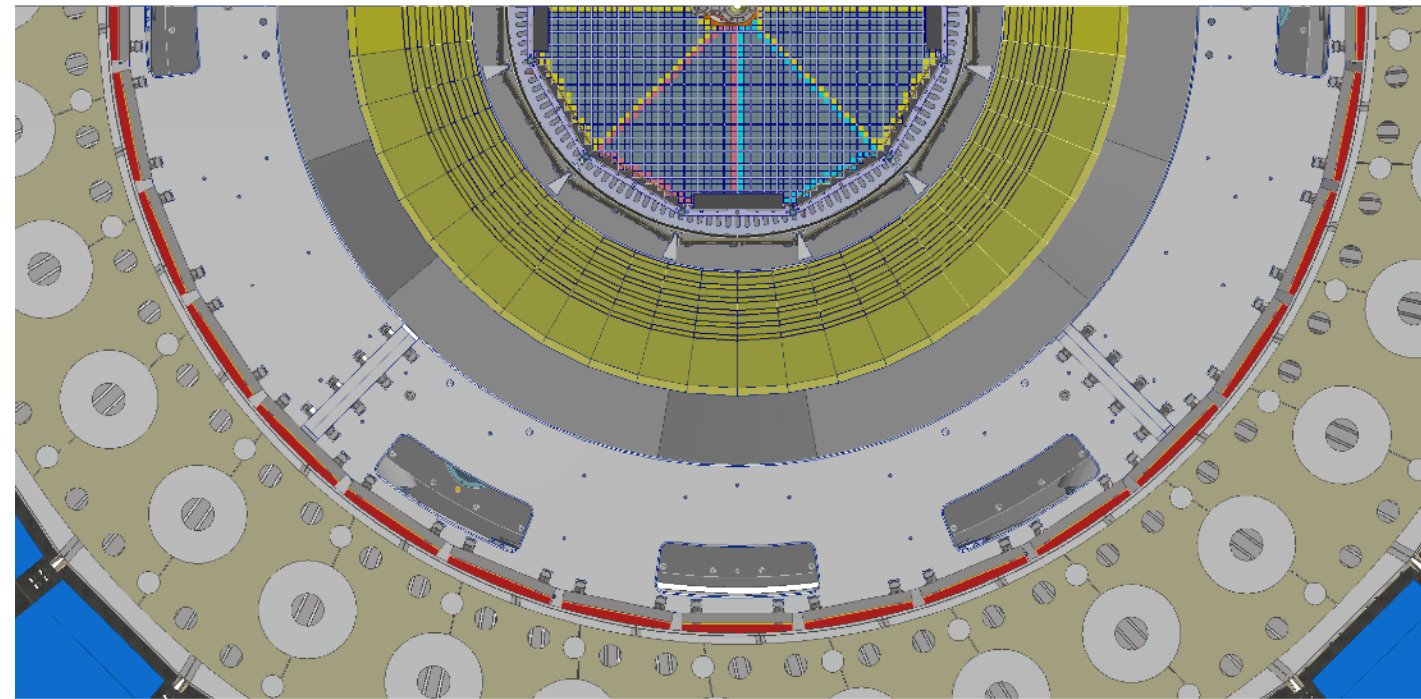
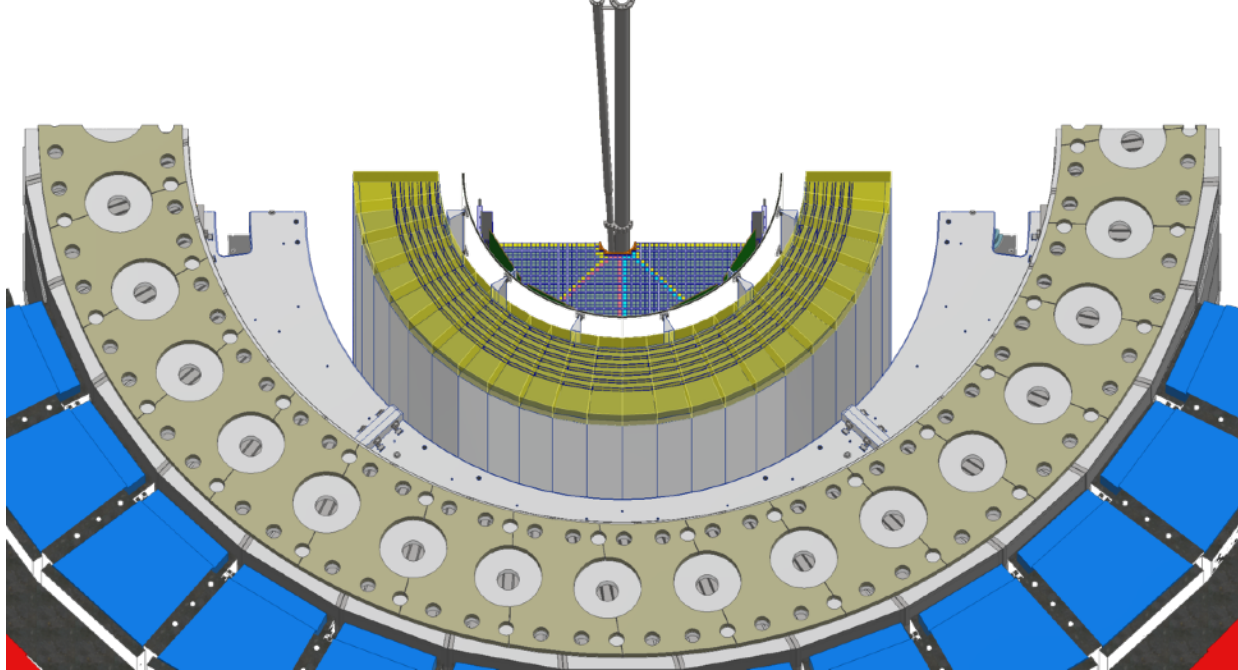
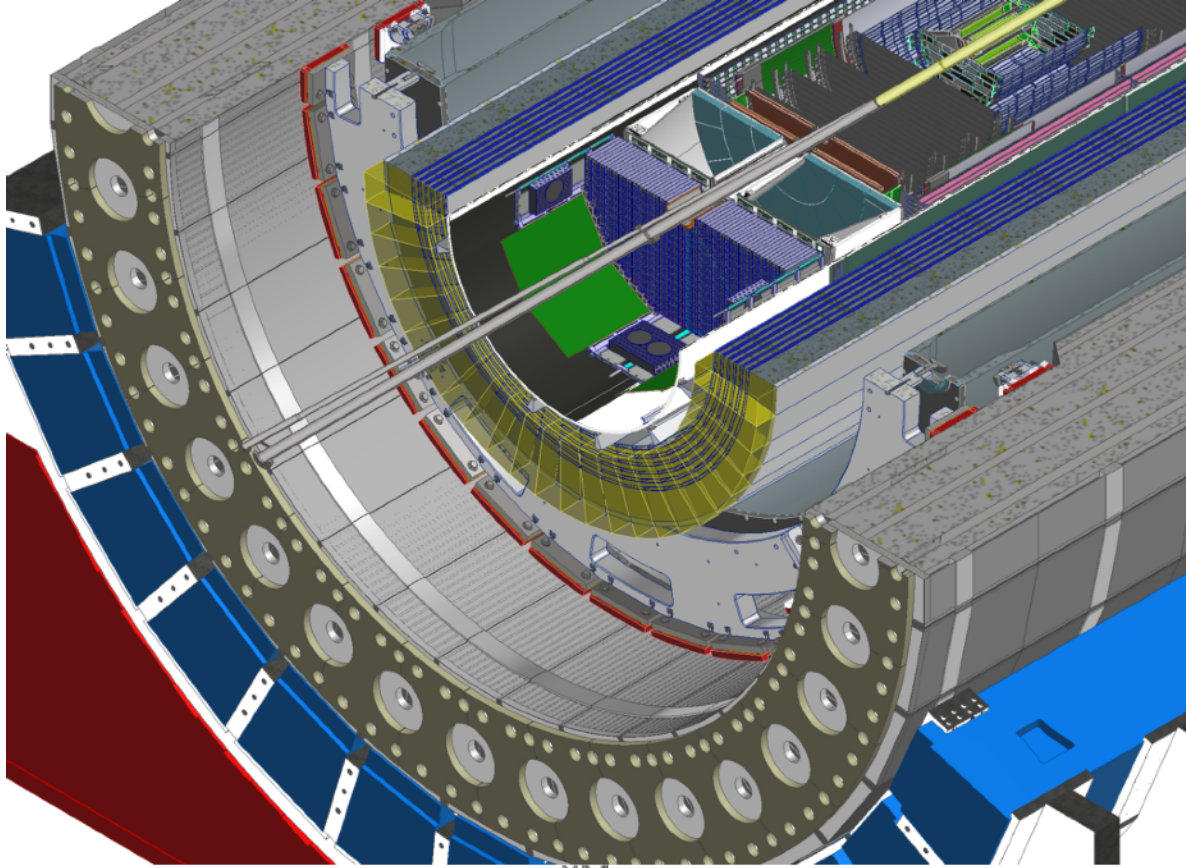
ETC window thru SiPM/Cooling layers

BNL Project Drawings

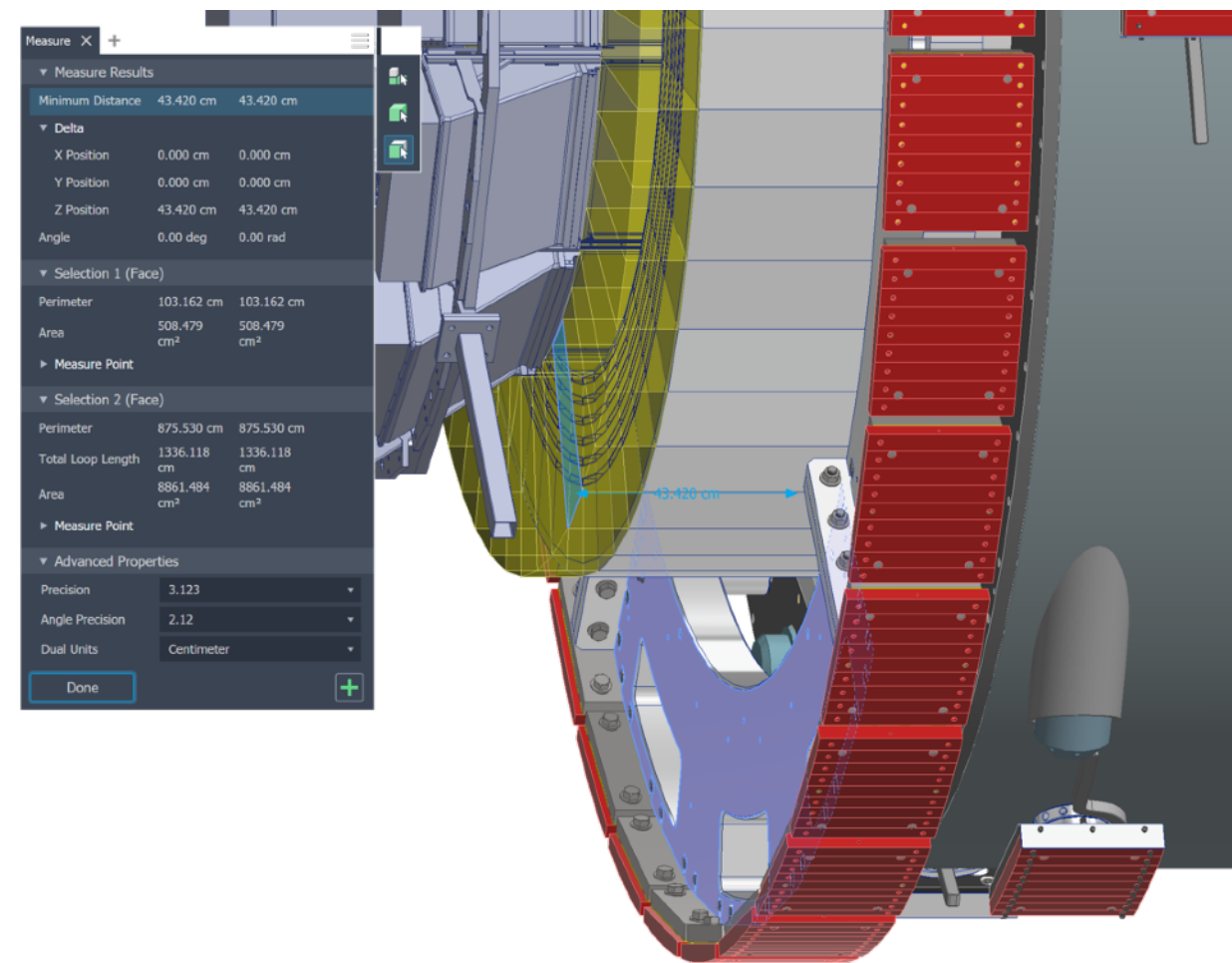
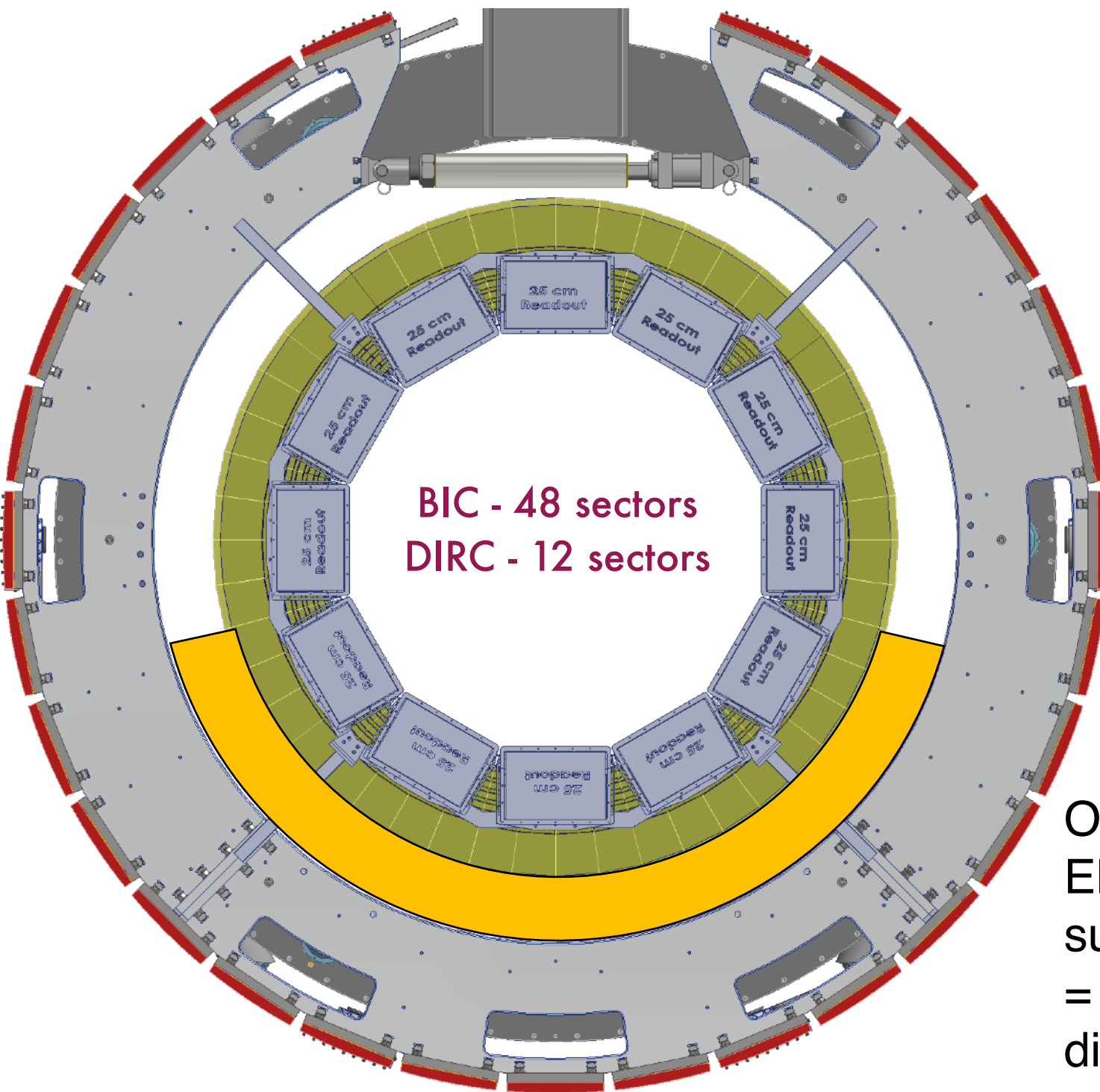


BNL Project Drawings

Backward end views



BNL Project Drawings

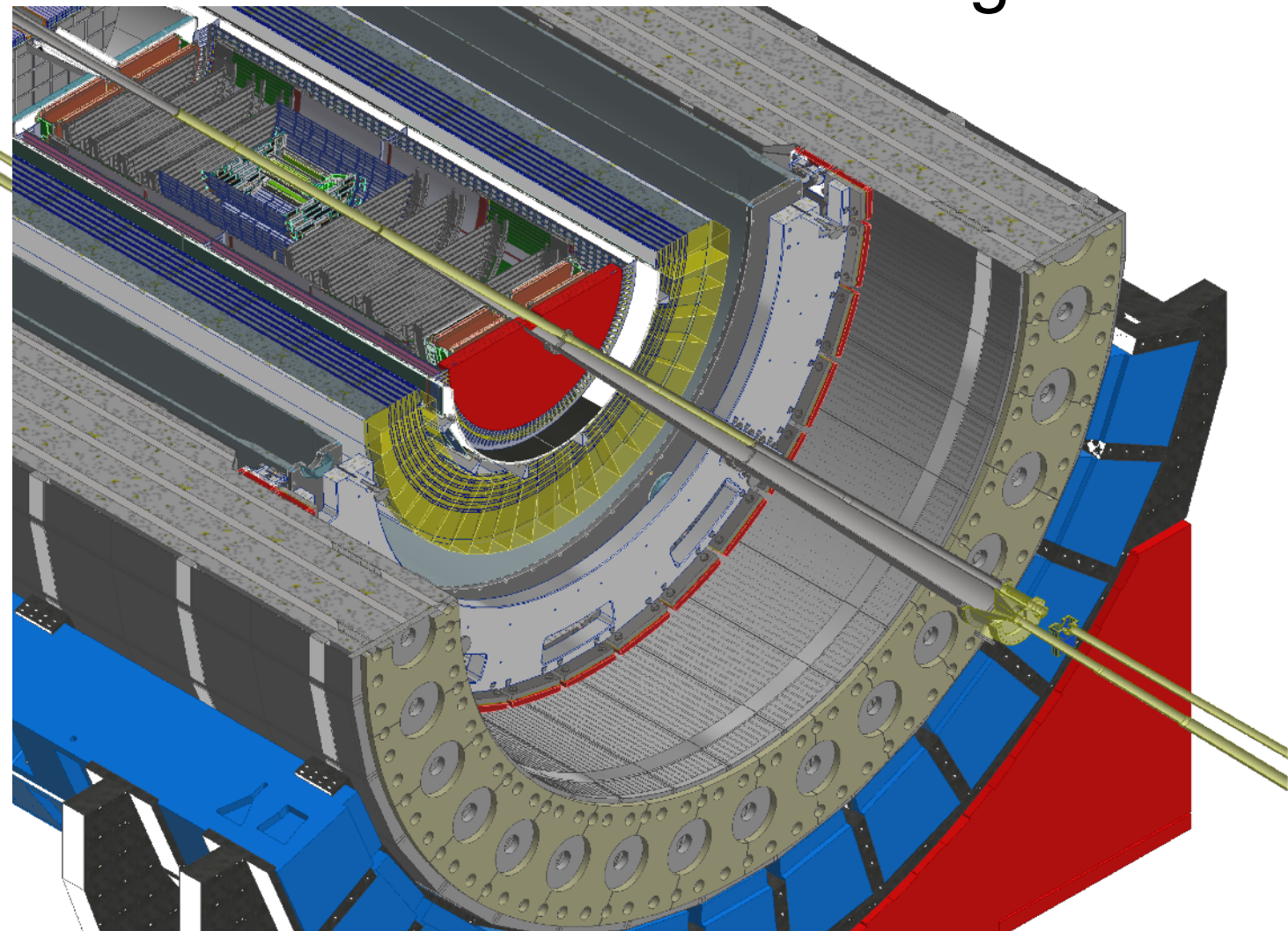
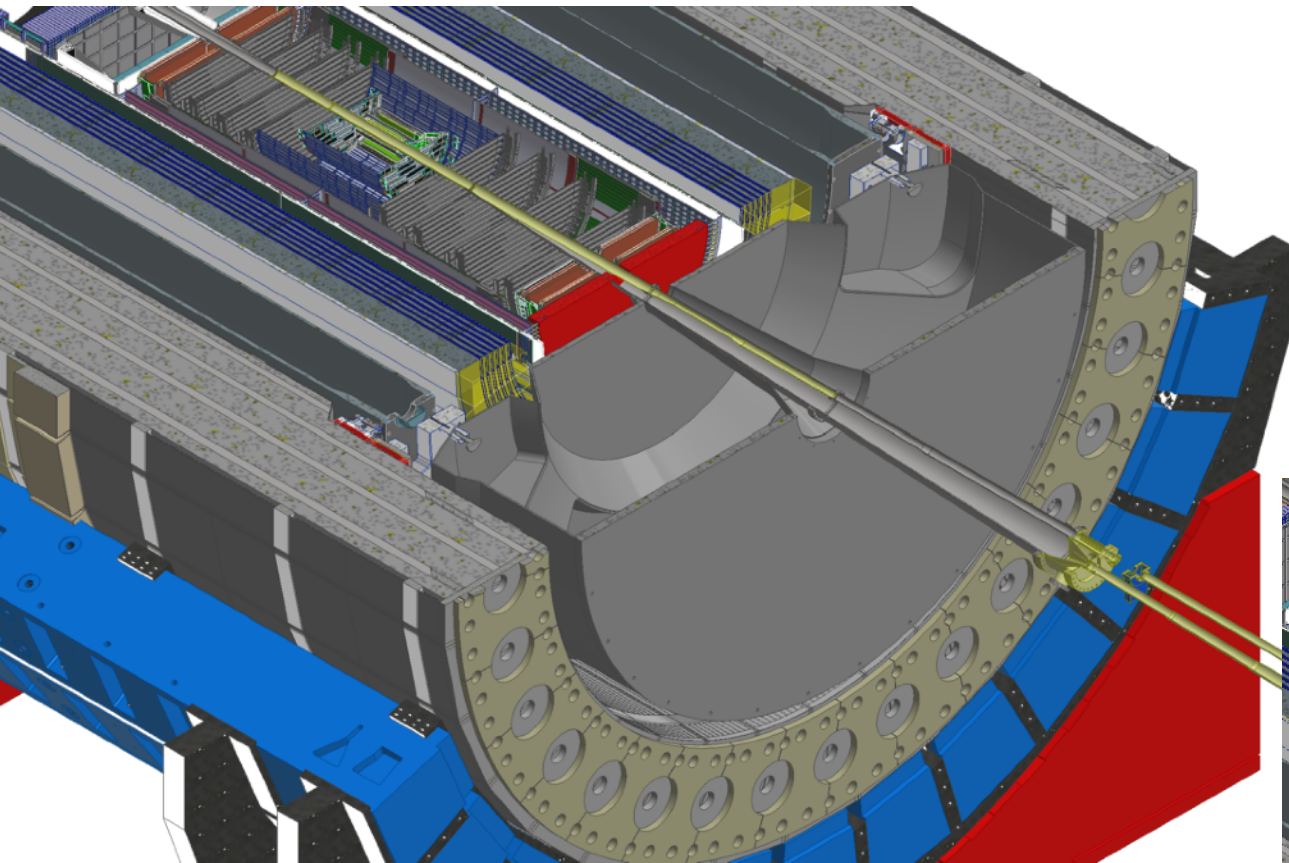


Orange is proposed support location. The EMCAL supports would sit on top of the inner support rings. The inner support rings sit at $Z = -217.17$ cm to -227.33 cm in the backward direction and $Z = 194.310$ cm to $Z = 204.470$ cm in the forward direction. **In the backward direction the support will be simple and will support the EMCAL directly from the inner support rings. DIRC is an issue.**

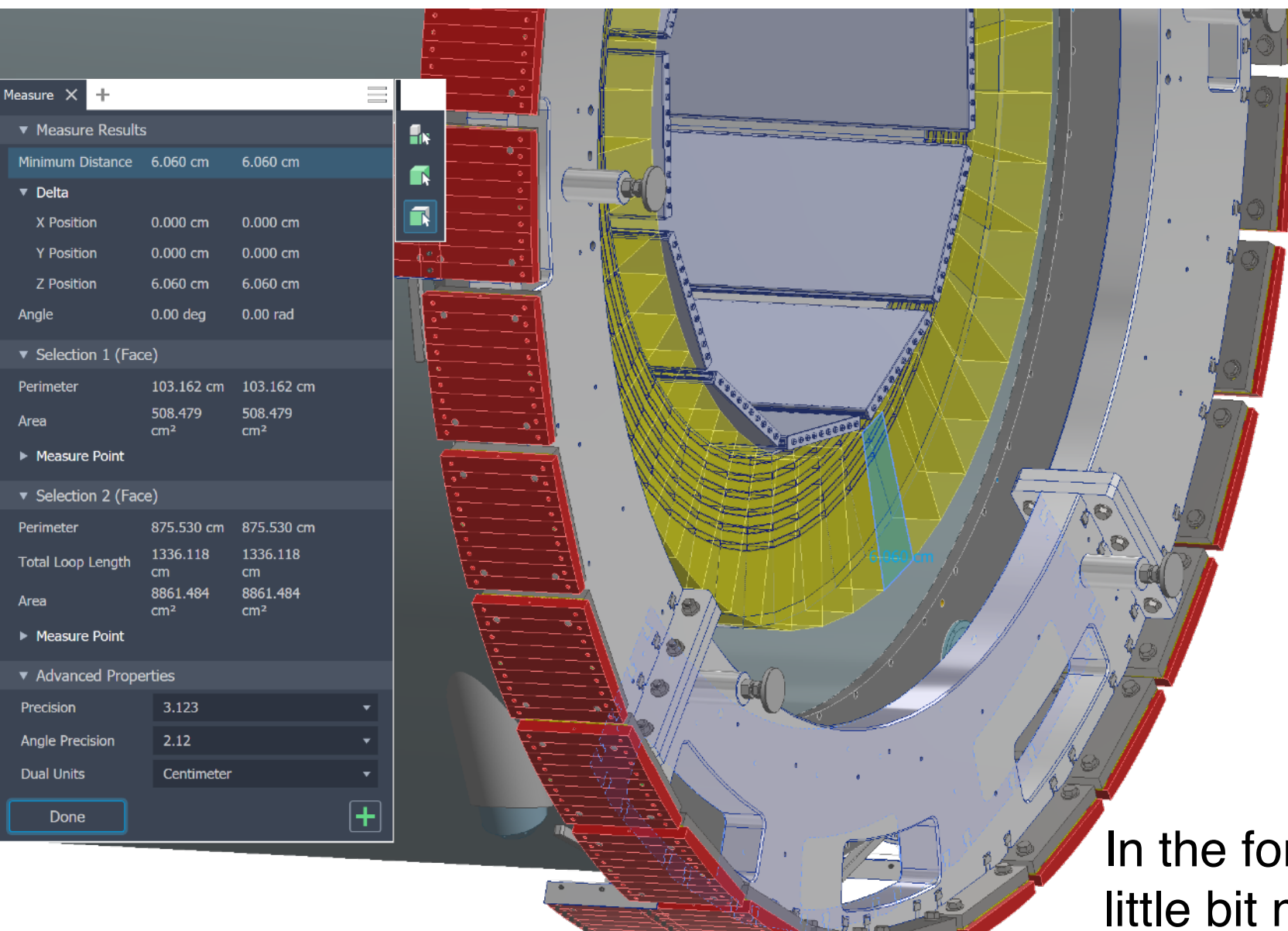
BNL Project Drawings

Forward end views

dRICH missing view

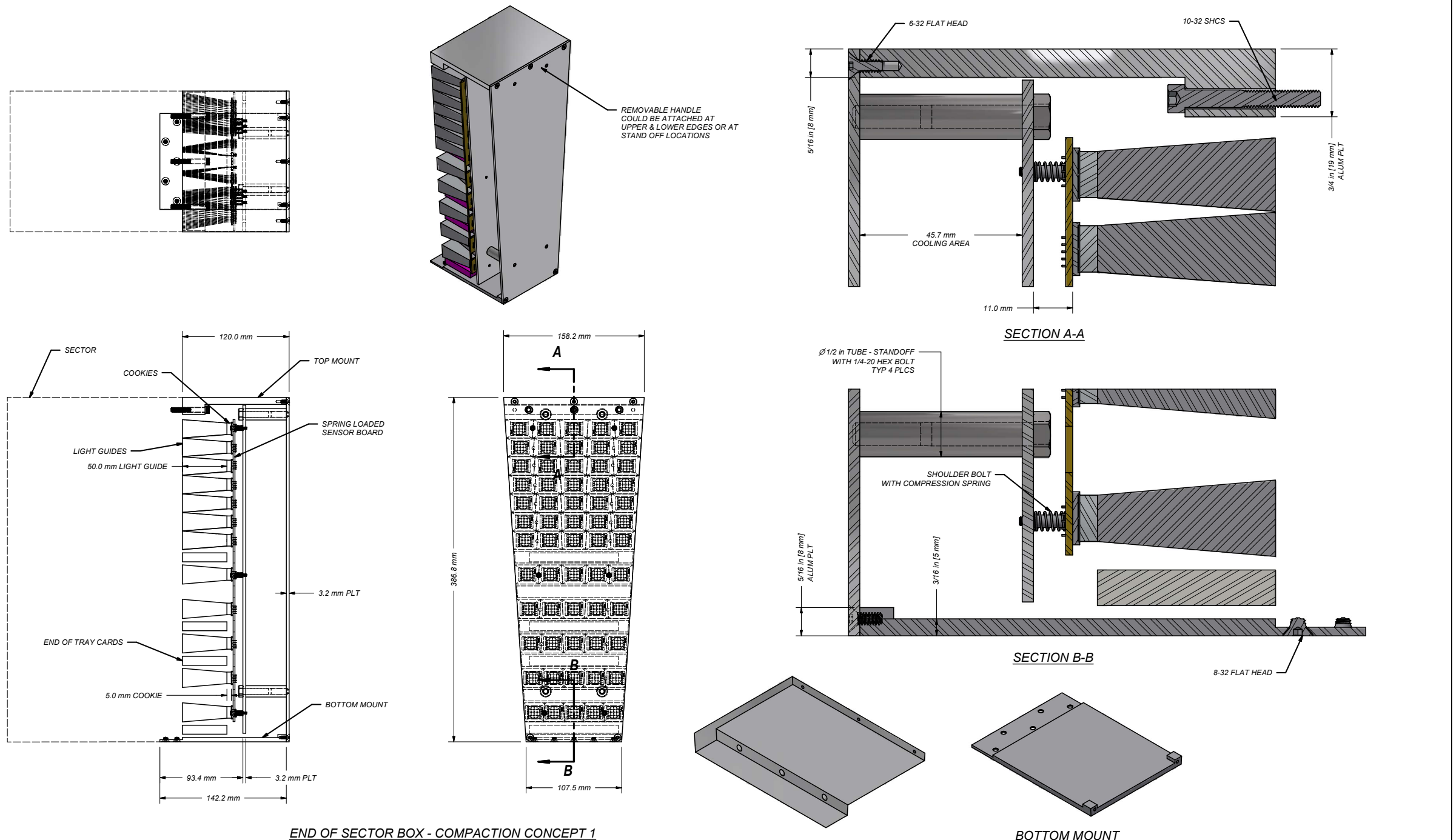


BNL Project Drawings



In the forward direction the support will be a little bit more complicated due to the support ring being past the EMCAL in Z. **Moving the electronics outward radially may not be possible.**

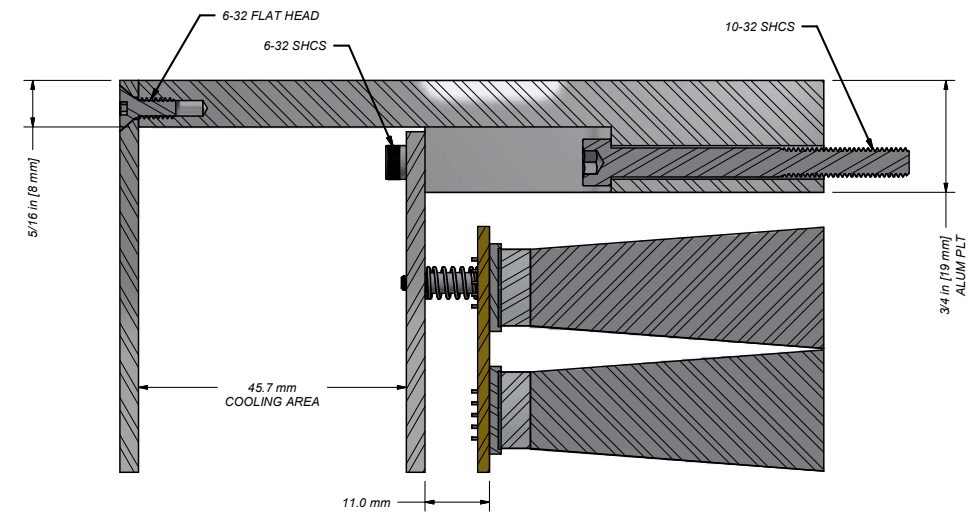
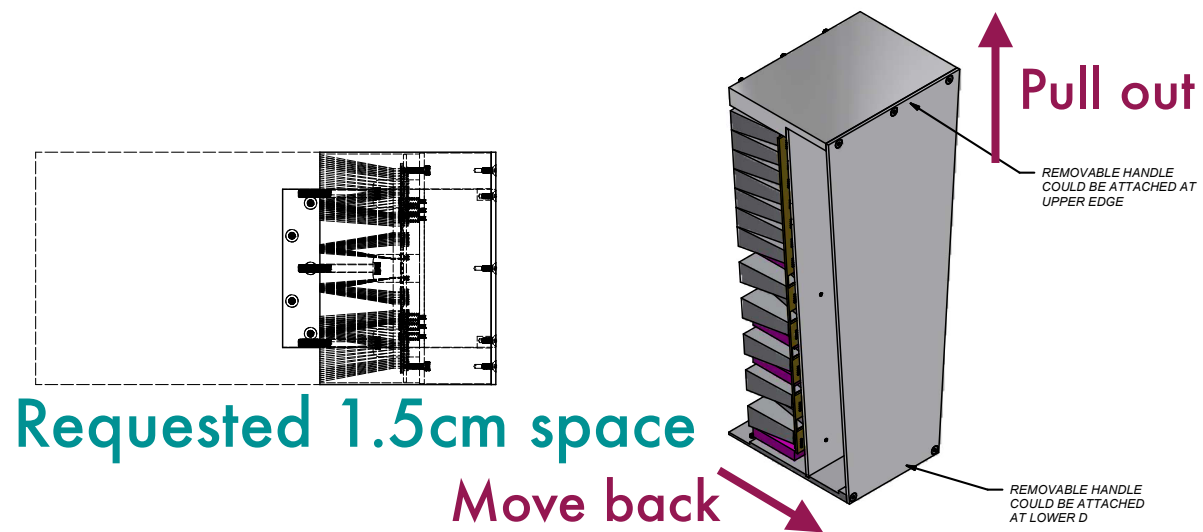
ESB Design - Concept 1 - Hadron End



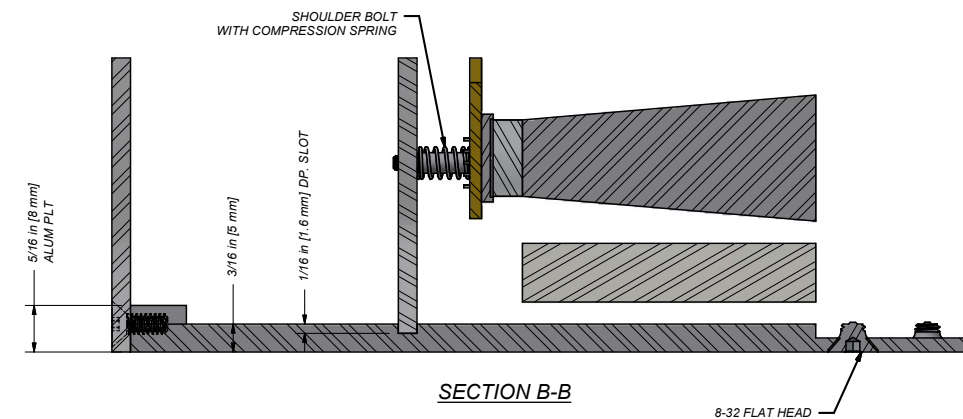
ESB removed along length

RELEASE FOR APPROVAL		04/DEC/2024	SGM	Z.P.	MANUFACTURING TOLERANCES - U.N.O.		CUSTOMER	
REV	DESCRIPTION	DATE	REV BY	APVD BY	SAW - ± 1/16		U of R	
					TORCH - ± 1/8		PROJECT	
					FAB - ± 1/16		BIC DETECTOR	
					MACHINING TOLERANCES - U.N.O.		SECTOR	
					CONCENTRICITY: 0.003 T.I.R.		ESB COMPACTION CONCEPT 1	
					BREAK EDGES: 0.015 x 45°		FILE #	
					Min. RADIUS: 0.010		71485-101	
					SURFACE FINISH		REV	
					ANGLE: ± 0.1°		A	

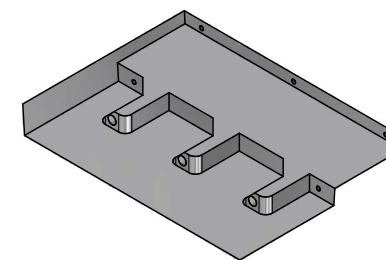
ESB Design - Concept 2: Electron End



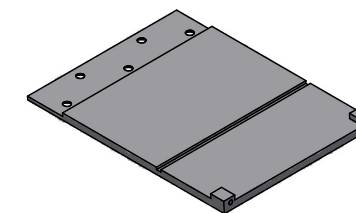
SECTION A-A



SECTION B-B



TOP MOUNT



BOTTOM MOUNT

END OF SECTOR BOX - COMPACTION CONCEPT 2

ESB removed along radius

A RELEASE FOR APPROVAL		03/DEC/2024	SGM	Z.P.	MANUFACTURING TOLERANCES - U.N.O.		CUSTOMER	
REV DESCRIPTION		DATE	REV BY	APVD BY	SAW - ± 1/16		U of R	
					TORCH - ± 1/8		PROJECT	
					FAB - ± 1/16		BIC DETECTOR	
					CONCENTRICITY: 0.003 T.I.R.		SECTOR	
					MACHINING		ESB COMPACTION CONCEPT 2	
					BREAK EDGES: 0.015 x 45°		FILE #	
					Min. RADIUS: 0.010		71485-102	
					SURFACE FINISH		REV	
					ANGLE: ± 0.1°		A	

M&S

- New tooling received by RMS.
 - 10 new LGs will be made next, and compared to those for SFILs
- New order will be placed to Eljen for 3-mm and 2-mm thick cookie sheets.
- Waiting for Hamamatsu quote on 130 S14 SiPMs.



Different degrees of polish



New diamond-carbide cutter

ESB Design - Cooling

- Manitoba will look at: a) thermal conduction of Astropix through the lead SciFi and b) ESB cooling for SiPM stability and ETC and CALOROC heat removal.
- Use thermal pad or metal-core PCB for implementation of a single copper line.
- Forced air in the ESB?
- Ross Machine Shop can build the cooling lines. Assuming a cooling snake that runs by all the SiPMs, we could fit a 1-cm-diameter copper line between SiPM rows.
- NASA: roughly 1 W per ETC card (the FPGA basically), so 4 W per box; Connector at the end of each the Astropix tray, then we can use cables to go to the ETC cards which could sit in the volume under the CALOROC and receive heat removal from the pad or metal-core PCB.
- Aram says that assuming his SiPM summing and amplification, 8 W total per ESB box.
- HGCROC chip: 4W each and operate at 40 C without cooling (from interface document)

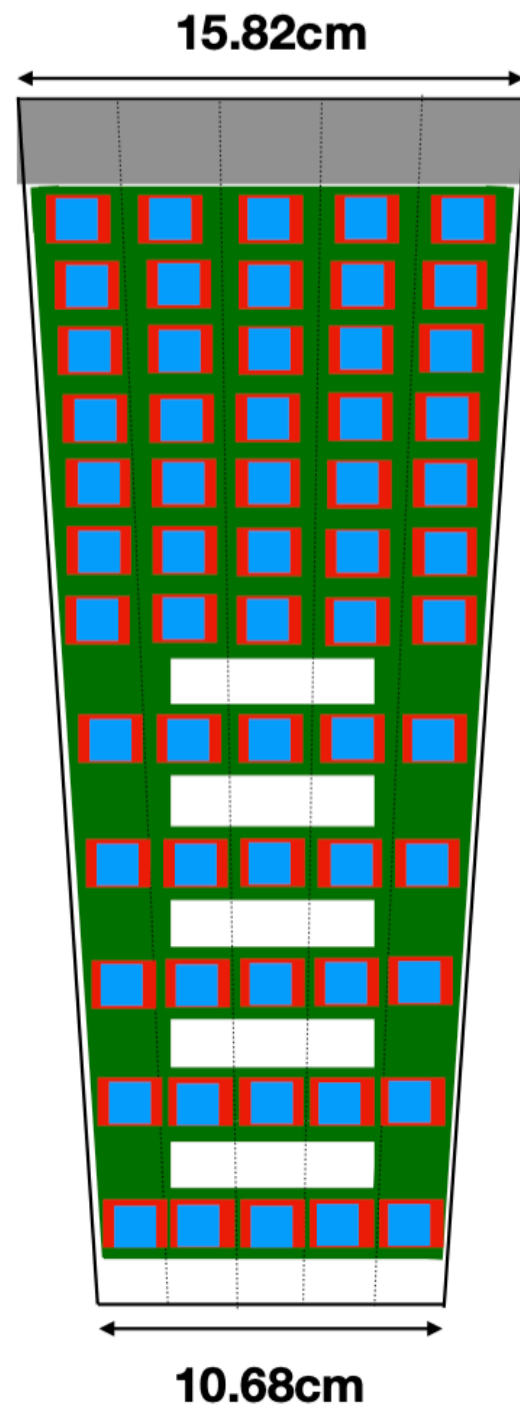
BIC in-person meeting: ESB session April 10, 2025

12:00	Lunch	
13:00	D172, Building 241	12:00 - 13:30
	ESB Design and Interfaces	<i>Zisis Papandreou</i>
	D172, Building 241	13:30 - 13:50
	ESB Cooling	
	D172, Building 241	13:50 - 14:00
14:00	HGCROC Readout	<i>Norbert Novitzky</i>
	D172, Building 241	14:00 - 14:20
	ETC Design Interfaces	
	D172, Building 241	14:20 - 14:40
	ESB & DAQ PDR and future plans (deliverables)	
	D172, Building 241	14:40 - 15:00
15:00	Break	
	D172, Building 241	15:00 - 15:30

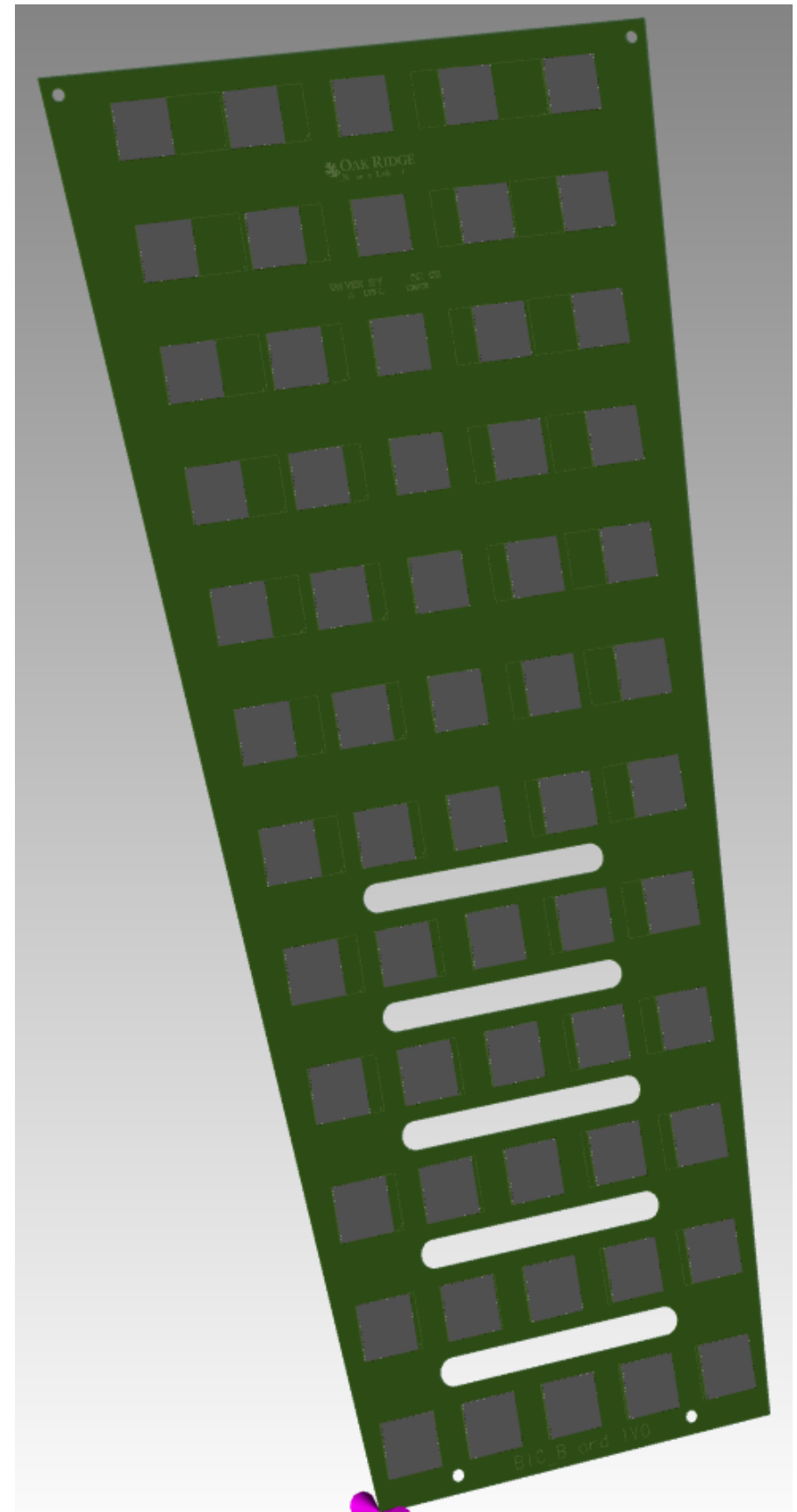
Summary

- **ESB Bi-weekly meetings, 8am CDT** (alternating weeks with System Testing at same time slot)
- **ESB design advancing but lots to do:**
 - ESB-BabyBCAL (Apr 2025), ESB-BIC (Nov 2025)
 - CALOROC: ORNL
 - ETCs: NASA / ANL / Regina
 - Cooling: Manitoba / Regina
- Merlin Project Schedule, Spreadsheets, Cooling
- R&D day April 16-17 / Project Review August

Backup slides

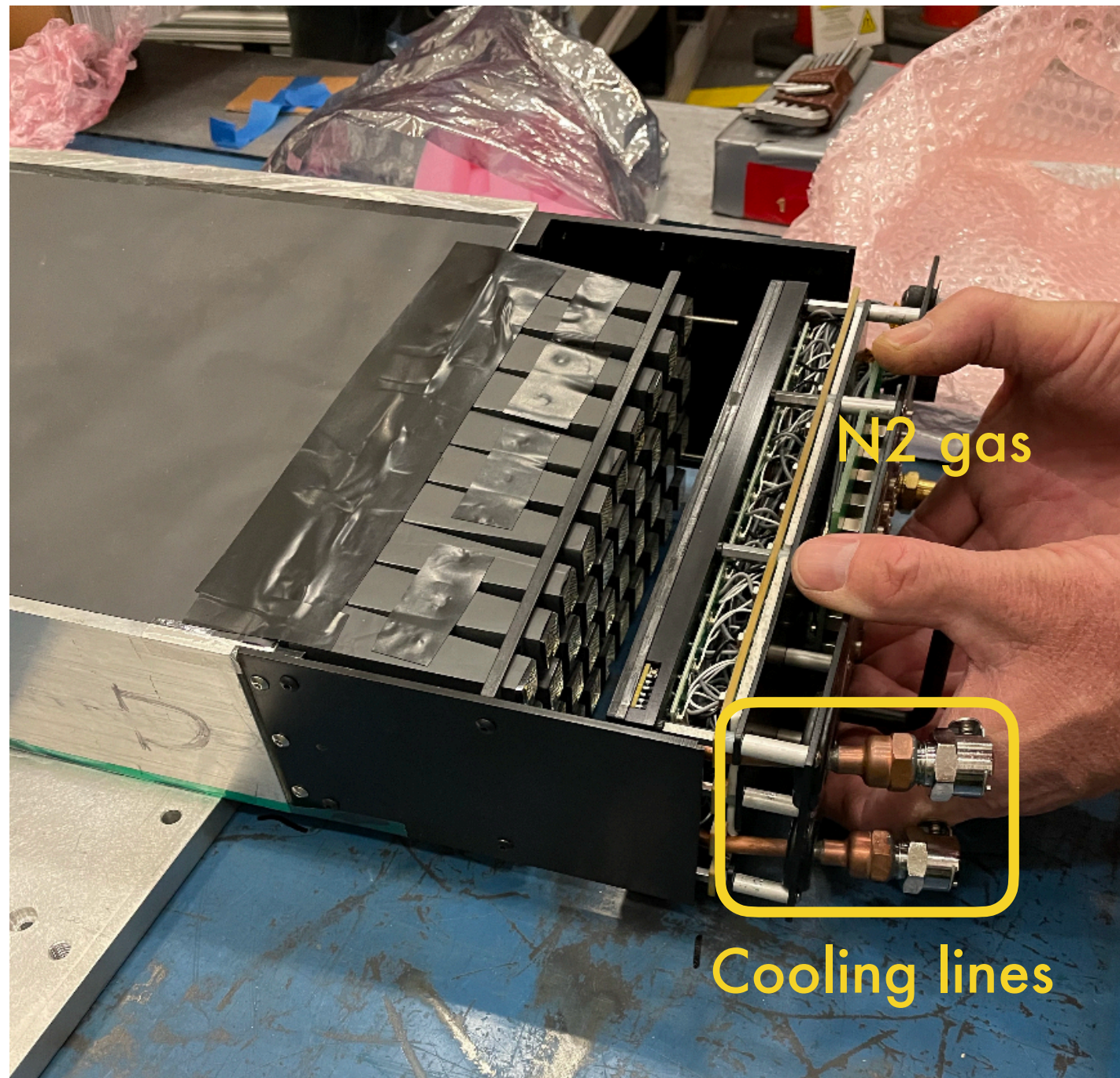


Testing at ORNL



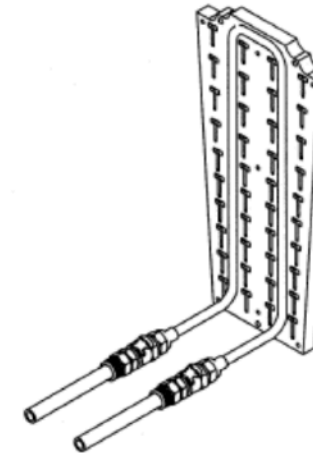
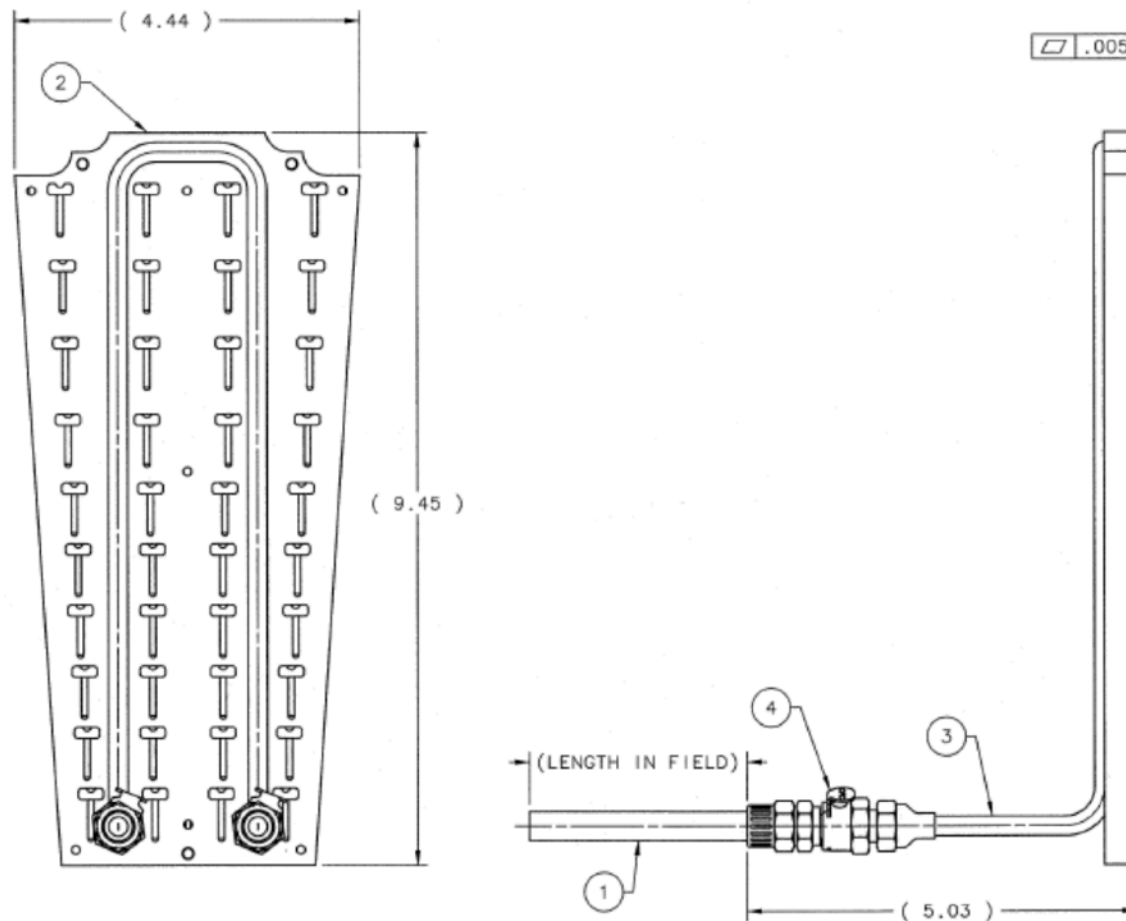


BCAL "Wedges"



- Contiguous LG stacking
- LG-SiPM air gap
- BIC: Si cookie
- Spring loading
- Integrated ESB for installation ease

Cooling Assembly



NOTES:

1. SUGGESTED SOURCES OR JLAB APPROVED ALTERNATE:

COLDER PRODUCTS COMPANY
1-800-444-2474
www.colder.com

2. SOLDER ITEM 2 TO ITEM 3 IN SUCH A WAY TO ENSURE GOOD THERMAL AND MECHANICAL CONTACT.
4. SOLDERING ITEMS 2 & 3 TOGETHER USING 50/50 TIN-LEAD SOLDER WITH GENERAL PURPOSE FLUX USING ANY STANDARD SOLDERING PROCESS.
5. PROCESS SHOULD ENSURE COMPONENT TEMPERATURES ARE MAINTAINED BELOW 800°F.
6. THOROUGHLY CLEAN ALL FLUXES WITH APPROPRIATE METHODS TO ENSURE REMAINING FLUX IS COMPLETELY REMOVED OR RENDERED NON-CORROSIVE
7. LENGTH OF ITEM 1 TO BE DECIDED IN FIELD TO ALLOW FOR APPROPRIATE LENGTH AND THEN INSTALLED AS SHOWN.

2	4	COLDER PRODUCTS MCD1002	1/8 NPT VALVED COUPLING BODY	BRASS	1
1	3	D00000-01-07-2041	COOLING TUBE W/FITTINGS		
1	2	D00000-01-07-2040	COOLING PLATE		
2	1	D00000-01-07-1022	HOSE ASSY		

DOCUMENT CONTROL STAMP		UNITED STATES DEPARTMENT OF ENERGY		Jefferson Lab Thomas Jefferson National Accelerator Facility		Newport News Virginia	
MATERIAL SEE PARTS LIST		THIRD ANGLE PROJECTION		DRAWN C. HUTTON		DATE 01/08/11	
FINISH MACHINED SURFACES DEBUR & BREAK ALL SHARP EDGES		TOLERANCES ARE: FRACTIONS DECIMAL ANGLES N/A .X ±.1 .XXX ±.005		CHECKED [Signature]		DATE 2/1/11	
DO NOT SCALE DRAWING		TRACKING NO. N/A		APPROVALS [Signature]		DATE 2/1/11	
		SIZE D		DWG. NO. D00000-01-07-1021		REV. -	
		SCALE 1:1		SHEET 1 OF 1			